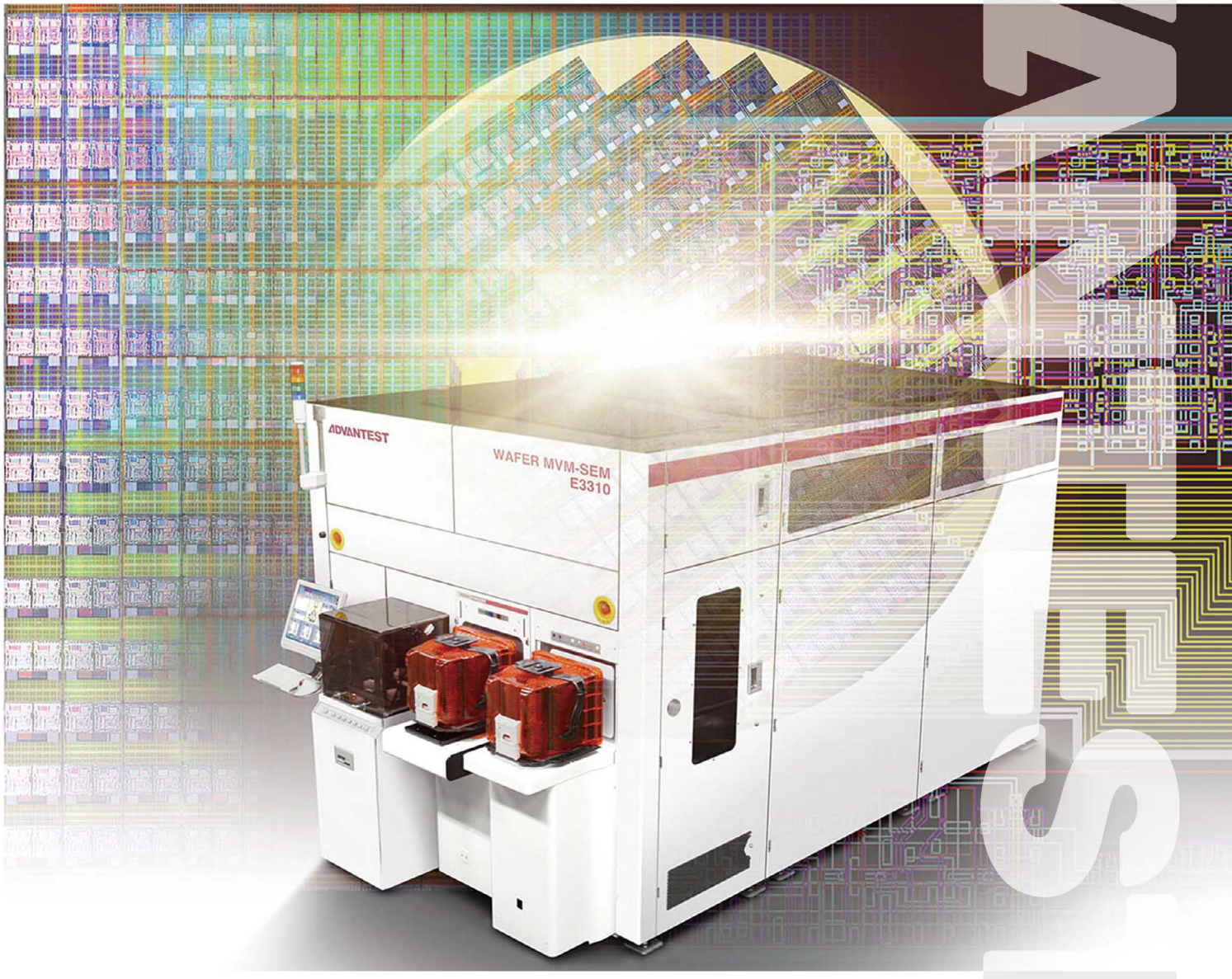
ADVANTEST®

WAFER MVM-SEM®

E3310

Multi Vision Metrology SEM supports next-generation wafers



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The E3310 is a WAFER MVM-SEM* for next generation wafers, supporting 1Xnm node process development and volume production at the 22nm node and beyond. With its high-speed carrier system employing a dual arm vacuum robot, and low-vibration platform to improve measurement accuracy, the E3310 delivers high throughput and performance for wafer measurements. Its multi detector configuration and unique 3D measurement algorithm also enable stable, high-accuracy measurement of 3D transistor technologies such as FinFET. The E3310 makes a significant contribution to reducing process development turnaround time and improves productivity for next-generation devices.

*Multi Vision Metrology Scanning Electron Microscope

Support for diverse wafer types

- **Silicon wafer**
- **AlTiC wafer**
- **Quartz wafer**
- **Silicon carbide wafer**

Wafer size supported: 150mm - 300mm (depends on wafer type)

Advanced electron-optical column design

The E3310 inherits the proprietary column design and unique electron beam scanning technology employed by the E3630, which has a large installed base in the photomask sector. Advantest's unique architecture achieves high resolution by maintaining a high voltage inside the column, and a newly developed object lens significantly reduces chromatic aberration and further improves resolution in the low acceleration range.

Accurate, high-precision positioning technology

A new stage positioning system, charge control function, and contamination reduction technology enable the stable positioning of objects for measurement even at high SEM magnification, allowing high throughput and easy observation.

Supports evolving wafer processes

The E3310's multi-detector configuration allows it to achieve stable, highly accurate measurements at the 1Xnm node. It also features a proprietary detection algorithm, enabling measurement of 3D FinFET architectures, and contributes to reducing process development turnaround time by providing new process control information.

Rich range of applications

- Large field-of-view SEM image enables automatic multipoint measurement function
- Pattern contour detection/GDS output function from SEM image
- Displays 3D images generated by multi-detector system
- SECS/GEM function for factory automation

Please refer to product manual for complete system specifications.
Specifications may change without notification.

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https://www.advantest.com/

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